Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-8. (Canceled)

9. (Currently Amended) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a light emitting element emitting red light, a light emitting element emitting green light and a light emitting element emitting blue light [[at]] over a front surface of a substrate;

polishing a back surface of the substrate ~~by a chemical mechanical polishing method~~ to ~~thereby~~ reduce a thickness of the substrate to less than ~~300 micrometers~~ a pixel pitch; and

bonding a ~~red~~ color filter ~~adjacent to the light emitting element emitting red light, a green color filter adjacent to the light emitting element emitting green light and a blue color filter adjacent to the light emitting element emitting blue light at~~ comprising at least a red colored layer, a green colored layer and a blue colored layer to the polished back surface of the substrate,

wherein the red light is passed through the substrate and the red colored layer,

wherein the green light is passed through the substrate and the green colored layer, and

wherein the blue light is passed through the substrate and the blue colored layer.

~~wherein the red color filter comprises a red colored layer, the green color filter comprises a green colored layer, and the blue color filter comprises a blue colored layer, and~~

~~wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.~~

10. (Currently Amended) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a thin film transistor and a light emitting element emitting red light, a light emitting element emitting green light and a light emitting element emitting blue light being electrically connected to the thin film transistor [[at]] over a front surface of a substrate;

polishing a back surface of the substrate ~~by a chemical mechanical polishing method~~ to ~~thereby~~ reduce a thickness of the substrate to less than ~~300 micrometers~~ a pixel pitch; and

bonding ~~a red color filter adjacent to the light emitting element emitting red light, a green color filter adjacent to the light emitting element emitting green light and a blue color filter adjacent to the light emitting element emitting blue light at~~ a color filter comprising at least a red colored layer, a green colored layer and a blue colored layer to the polished back surface of the substrate,

wherein the red light is passed through the substrate and the red colored layer,

wherein the green light is passed through the substrate and the green colored layer, and

wherein the blue light is passed through the substrate and the blue colored layer.

~~wherein the red color filter comprises a red colored layer, the green color filter comprises a green colored layer, and the blue color filter comprises a blue colored layer, and~~

~~wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.~~

11. (Currently Amended) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a base film over a first substrate;

forming a plurality of light emitting elements emitting red light, a plurality of light emitting elements emitting green light and a plurality of light emitting elements emitting blue light in a matrix form ~~at a front surface of a first substrate~~ over the base film;

~~polishing a back surface of the first substrate by a chemical mechanical polishing method to thereby reduce a thickness of the first substrate to less than 300 micrometers; and~~

separating the first substrate from the base film; and

bonding a transparent substrate comprising ~~at least a red colored layer adjacent to the light emitting element emitting red light, a green color filter adjacent to the light emitting element emitting green light and a blue color filter adjacent to the light emitting element emitting~~

~~blue light at a back surface of the first substrate,~~ at least a red colored layer, a green colored layer and a blue colored layer to the base film,

wherein the red light is passed through the base film and the red colored layer,

wherein the green light is passed through the base film and the green colored layer,

wherein the blue light is passed through the base film and the blue colored layer.

~~said method further comprising a step of bonding a polarization plate to the transparent substrate,~~

~~wherein the red color filter comprises a red colored layer, the green color filter comprises a green colored layer, and the blue color filter comprises a blue colored layer, and~~

~~wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.~~

12. (Currently Amended) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a base film over a first substrate;

forming a semiconductor element and a light emitting element emitting red light, a light emitting element emitting green light and a light emitting element emitting blue light being electrically connected to the semiconductor element ~~at a front surface of a first substrate~~ over the base film;

~~polishing a back surface of the first substrate by a chemical mechanical polishing method to thereby reduce a thickness of the first substrate to less than 300 micrometers; and~~

separating the first substrate from the base film; and

bonding a transparent substrate comprising ~~at least a red colored layer adjacent to the light emitting element emitting red light, a green color filter adjacent to the light emitting element emitting green light and a blue color filter adjacent to the light emitting element emitting blue light at a back surface of the first substrate,~~ at least a red colored layer, a green colored layer and a blue colored layer to the base film,

wherein the red light is passed through the base film and the red colored layer,

wherein the green light is passed through the base film and the green colored layer,

wherein the blue light is passed through the base film and the blue colored layer.

~~said method further comprising a step of bonding a polarization plate to the transparent substrate,~~

~~wherein the red color filter comprises a red colored layer, the green color filter comprises a green colored layer, and the blue color filter comprises a blue colored layer, and~~

~~wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.~~

13. (Canceled)

14. (Presently Presented) A method according to claim 11, wherein the transparent substrate comprises a polymeric material.

15-18. (Canceled)

19. (Presently Presented) A method according to claim 12, wherein the transparent substrate comprises a polymeric material.

20-22. (Canceled)

23. (Withdrawn): A method of manufacturing a light emitting device comprising:

providing a first substrate having a first surface and a second surface opposite to said the first surface;

forming a first electrode over the first surface of the first substrate;

forming an electroluminescence layer over the first electrode; and

forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

forming a plurality of color layers over a first surface of a second substrate;

fixing the second substrate to said first substrate with said plurality of color layers interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

24. (Withdrawn) The method according to claim 23 wherein said light emitting device is a passive matrix display device.

25. (Withdrawn) The method according to claim 23 wherein said light emitting device is an active matrix display device.

26. (Withdrawn) The method according to claim 23 wherein said electroluminescence layer comprises an organic electroluminescence material.

27. (Withdrawn) A method of manufacturing a light emitting device comprising:

providing a first substrate having a first surface and a second surface opposite to said the first surface;

forming a first electrode over the first surface of the first substrate;

forming an electroluminescence layer over the first electrode; and

forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

polishing the second surface of the first substrate to thin the first substrate;

forming a plurality of color layers over a first surface of a second substrate;

fixing the second substrate to the thinned first substrate with said plurality of color layers interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

28. (Withdrawn) The method according to claim 27 wherein said light emitting device is a passive matrix display device.

29. (Withdrawn) The method according to claim 27 wherein said light emitting device is an active matrix display device.

30. (Withdrawn) The method according to claim 27 wherein said electroluminescence layer comprises an organic electroluminescence material.

31. (Withdrawn) The method according to claim 27 wherein a thickness of said first substrate after the step of polishing is 300 μm or less.

32. (Withdrawn) A method of manufacturing a light emitting device comprising:

providing a first substrate having a first surface and a second surface opposite to said the first surface;

forming a first electrode over the first surface of the first substrate;

forming an electroluminescence layer over the first electrode; and

forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

providing a second substrate having a first surface and a second surface opposite to said second surface wherein said second substrate comprises a plastic material and each of the first and second surfaces of the second substrate are coated with a protective film;

forming a plurality of color layers over the second substrate;

fixing the second substrate to said first substrate with said plurality of color layers interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

33. (Withdrawn) The method according to claim 32 wherein said light emitting device is a passive matrix display device.

34. (Withdrawn) The method according to claim 32 wherein said light emitting device is an active matrix display device.

35. (Withdrawn) The method according to claim 32 wherein said electroluminescence layer comprises an organic electroluminescence material.

36. (Withdrawn) The method according to claim 32 wherein said protective film comprises diamond like carbon.

37. (Withdrawn) A method of manufacturing a light emitting device comprising:

providing a first substrate having a first surface and a second surface opposite to said the first surface;

forming a first electrode over the first surface of the first substrate;

forming an electroluminescence layer over the first electrode;

polishing the second surface of the first substrate to thin the first substrate;

forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

providing a second substrate having a first surface and a second surface opposite to said second surface wherein said second substrate comprises a plastic material and each of the first and second surfaces of the second substrate are coated with a protective film;

forming a plurality of color layers over the second substrate;

fixing the second substrate to the thinned first substrate with said plurality of color layers; interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

38. (Withdrawn) The method according to claim 37 wherein said light emitting device is a passive matrix display device.

39. (Withdrawn) The method according to claim 37 wherein said light emitting device is an active matrix display device.

40. (Withdrawn) The method according to claim 37 wherein said electroluminescence layer comprises an organic electroluminescence material.

41. (Withdrawn) The method according to claim 37 wherein a thickness of said first substrate after the step of polishing is 300 μm or less.

42. (Withdrawn) The method of claim 9 wherein the light emitting element comprises an electroluminescence material.

43. (Withdrawn) The method of claim 10 wherein the light emitting element comprises an electroluminescence material.

44. (Withdrawn) The method of claim 11 wherein the light emitting element comprises an electroluminescence material.

45. (Withdrawn) The method of claim 12 wherein the light emitting element comprises an electroluminescence material.

46. (Canceled)

47. (Currently Amended) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a light emitting element emitting red light, a light emitting element emitting green light and light emitting element emitting blue light at a front surface of a first substrate;

polishing a back surface of the first substrate ~~by a chemical mechanical polishing method~~ to ~~thereby~~ reduce a thickness of the first substrate to less than ~~300 micrometers~~ a pixel pitch; and

bonding a transparent substrate comprising ~~at least a red colored layer adjacent to the light emitting element emitting red light, a green color filter adjacent to the light emitting element emitting green light and a blue color filter adjacent to the light emitting element emitting blue light at a~~ at least a red colored layer, a green colored layer and a blue colored layer to the back surface of the first substrate,

said method further comprising a step of bonding an antireflection film to the transparent substrate,

wherein the red light is passed through the substrate and the red colored layer,

wherein the green light is passed through the substrate and the green colored layer, and

wherein the blue light is passed through the substrate and the blue colored layer.

~~wherein the red color filter comprises a red colored layer, the green color filter comprises a green colored layer, and the blue color filter comprises a blue colored layer, and~~

~~wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.~~

48. (Previously Presented) The method according to claim 47, wherein the transparent substrate comprises a polymeric material.

49. (Canceled)

50. (Currently Amended) A method of manufacturing a light emitting device, said method comprising the steps of:

forming a semiconductor element and a light emitting element emitting red light, a light emitting element emitting green light and a light emitting element emitting blue light being electrically connected to the semiconductor element at a front surface of a first substrate;

polishing a back surface of the first substrate ~~by a chemical mechanical polishing method~~ to ~~thereby~~ reduce a thickness of the first substrate to less than ~~300 micrometers~~ a pixel pitch; and

bonding a transparent substrate comprising ~~at least a red colored layer adjacent to the light emitting element emitting red light, a green color filter adjacent to the light emitting element emitting green light and a blue color filter adjacent to the light emitting element emitting blue light at a~~ at least a red colored layer, a green colored layer and a blue colored layer to the back surface of the first substrate,

said method further comprising a step of bonding an antireflection film to the transparent substrate,

wherein the red light is passed through the substrate and the red colored layer,

wherein the green light is passed through the substrate and the green colored layer, and

wherein the blue light is passed through the substrate and the blue colored layer.

~~wherein the red color filter comprises a red colored layer, the green color filter comprises a green colored layer, and the blue color filter comprises a blue colored layer, and~~

~~wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.~~

51. (Previously Presented) The method according to claim 50, wherein the transparent substrate comprises a polymeric material.

52. (Canceled)

53. (Previously Presented) The method according to claim 9, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by deposition using a shadow mask.

54. (Previously Presented) The method according to claim 9, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by an ink jet method.

55. (Previously Presented) The method according to claim 9, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by a printing method.

56. (Previously Presented) The method according to claim 10, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by deposition using a shadow mask.

57. (Previously Presented) The method according to claim 10, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by an ink jet method.

58. (Previously Presented) The method according to claim 10, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by a printing method.

59. (Previously Presented) The method according to claim 11, wherein at least one of the plurality of light emitting elements emitting red light, the plurality of light emitting elements

emitting green light and the plurality of light emitting elements emitting blue light is formed by deposition using a shadow mask.

60. (Previously Presented) The method according to claim 11, wherein at least one of the plurality of light emitting elements emitting red light, the plurality of light emitting elements emitting green light and the plurality of light emitting elements emitting blue light is formed by an ink jet method.

61. (Previously Presented) The method according to claim 11, wherein at least one of the plurality of light emitting elements emitting red light, the plurality of light emitting elements emitting green light and the plurality of light emitting elements emitting blue light is formed by a printing method.

62. (Previously Presented) The method according to claim 12, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by deposition using a shadow mask.

63. (Previously Presented) The method according to claim 12, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by an ink jet method.

64. (Previously Presented) The method according to claim 12, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by a printing method.

65. (Previously Presented) The method according to claim 47, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by deposition using a shadow mask.

66. (Previously Presented) The method according to claim 47, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by an ink jet method.

67. (Previously Presented) The method according to claim 47, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by a printing method.

68. (Previously Presented) The method according to claim 50, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by deposition using a shadow mask.

69. (Previously Presented) The method according to claim 50, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by an ink jet method.

70. (Previously Presented) The method according to claim 50, wherein at least one of the light emitting element emitting red light, the light emitting element emitting green light and the light emitting element emitting blue light is formed by a printing method.

71. (New) The method according to claim 9, wherein the substrate is polished to a thickness of less than 300 micrometers.

72. (New) The method according to claim 9, wherein the substrate is polished by a chemical mechanical polishing method.

73. (New) The method according to claim 9, wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.

74. (New) The method according to claim 9, wherein at least one of the red colored layer, the green colored layer, and the blue colored layer includes a black pigment or carbon particles.

75. (New) The method according to claim 10, wherein the substrate is polished to a thickness of less than 300 micrometers.

76. (New) The method according to claim 10, wherein the substrate is polished by a chemical mechanical polishing method.

77. (New) The method according to claim 10, wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.

78. (New) The method according to claim 10, wherein at least one of the red colored layer, the green colored layer, and the blue colored layer includes a black pigment or carbon particles.

79. (New) The method according to claim 11, wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.

80. (New) The method according to claim 11, wherein at least one of the red colored layer, the green colored layer, and the blue colored layer includes a black pigment or carbon particles.

81. (New) The method according to claim 12, wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.

82. (New) The method according to claim 12, wherein at least one of the red colored layer, the green colored layer, and the blue colored layer includes a black pigment or carbon particles.

83. (New) The method according to claim 47, wherein the substrate is polished to a thickness of less than 300 micrometers.

84. (New) The method according to claim 47, wherein the substrate is polished by a chemical mechanical polishing method.

85. (New) The method according to claim 47, wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.

86. (New) The method according to claim 47, wherein at least one of the red colored layer, the green colored layer, and the blue colored layer includes a black pigment or carbon particles.

87. (New) The method according to claim 50, wherein the substrate is polished to a thickness of less than 300 micrometers.

88. (New) The method according to claim 50, wherein the substrate is polished by a chemical mechanical polishing method.

89. (New) The method according to claim 50, wherein at least two of the red colored layer, the green colored layer and the blue colored layer overlap with each other.

90. (New) The method according to claim 50, wherein at least one of the red colored layer, the green colored layer, and the blue colored layer includes a black pigment or carbon particles.